

N-Channel 30V(D-S) MOSFET

Product summary		
V_{DS}	30	V
$R_{DS(ON)}$ (at $V_{GS}=10V$) Typ.	21	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS}=4.5V$) Typ.	25	$m\Omega$
$I_D(T_A=25^\circ C)$	5.6	A

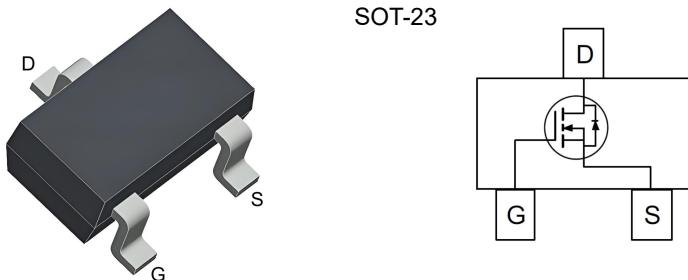
Features

- High density cell design for low $R_{DS(ON)}$
- Trench Power LV MOSFET technology
- RoHS Compliant

Applications

- Load Switch
- Power management

Pin Configuration



Packing Information

Device	Reel Size	Quantity(Min. Package)
ECDA3400	7"	3000pcs

Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Continuous Drain Current at $V_{GS}=10V$	$T_A=25^\circ C$	A
		$T_A=70^\circ C$	A
I_{DM}	Pulse Drain Current Tested ^A	23	A
P_D	Power Dissipation	$T_A=25^\circ C$	W
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JA}$	Thermal Resistance-Junction to ambient ^B	104	°C/W

Electrical Characteristics (at $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{D}}=250\text{uA}$	30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=30\text{V}, \text{V}_{\text{GS}}=0\text{V}$	--	--	1	uA
I_{GSS}	Gate-Body Leakage Current	$\text{V}_{\text{DS}}=0\text{V}, \text{V}_{\text{GS}}=\pm 12\text{V}$	--	--	± 100	nA
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_{\text{D}}=250\text{uA}$	0.65	0.9	1.5	V
$\text{R}_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_{\text{D}}=5.6\text{A}$	--	21	27	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_{\text{D}}=5\text{A}$	--	25	33	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=2.5\text{V}, \text{I}_{\text{D}}=3\text{A}$	--	33	51	$\text{m}\Omega$
V_{SD}	Forward Voltage	$\text{I}_{\text{S}}=5.6\text{A}, \text{V}_{\text{GS}}=0\text{V}$	--	--	1.2	V
I_{S}	Maximum Body-Diode Continuous Current		--	--	5.6	A
Dynamic Parameters						
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=15\text{V}$ $f=1\text{MHz}$	--	535	--	pF
C_{oss}	Output Capacitance		--	130	--	pF
C_{rss}	Reverse Transfer Capacitance		--	36	--	pF
Switching Parameters						
Q_{g}	Total Gate Charge	$\text{V}_{\text{DS}}=15\text{V}, \text{I}_{\text{D}}=5.6\text{A}$ $\text{V}_{\text{GS}}=4.5\text{V}$	--	4.8	--	nC
Q_{gs}	Gate-Source Charge		--	1.2	--	nC
Q_{gd}	Gate-Drain Charge		--	1.7	--	nC
$t_{\text{D(on)}}$	Turn-on Delay Time	$\text{V}_{\text{DD}}=15\text{V}, \text{I}_{\text{D}}=1\text{A}$, $\text{R}_{\text{GEN}}=2.8\Omega$, $\text{V}_{\text{GS}}=4.5\text{V}$	--	12	--	nS
t_{r}	Turn-on Rise Time		--	52	--	nS
$t_{\text{D(off)}}$	Turn-off Delay Time		--	17	--	nS
t_{f}	Turn-off Fall Time		--	10	--	nS

A. Pulse Test: Pulse Width $\leq 300\text{us}$, Duty cycle $\leq 2\%$.

B. Device mounted on FR-4 PCB, 1 inch x 1 inch x 0.062 inch.

Typical Characteristics

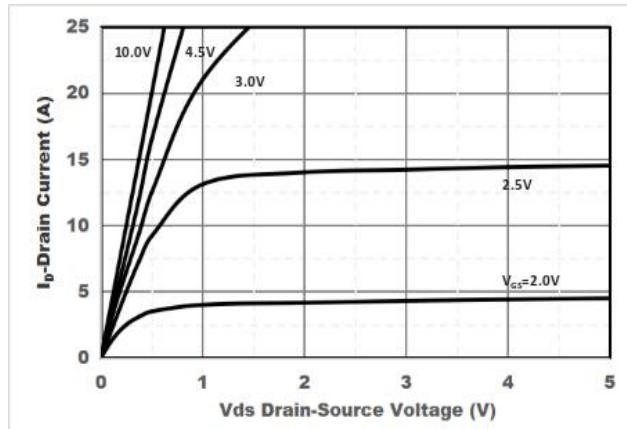


Figure1. Output Characteristics

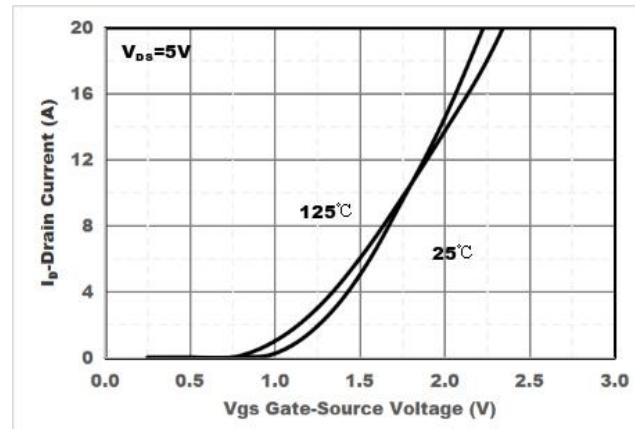


Figure2. Transfer Characteristics

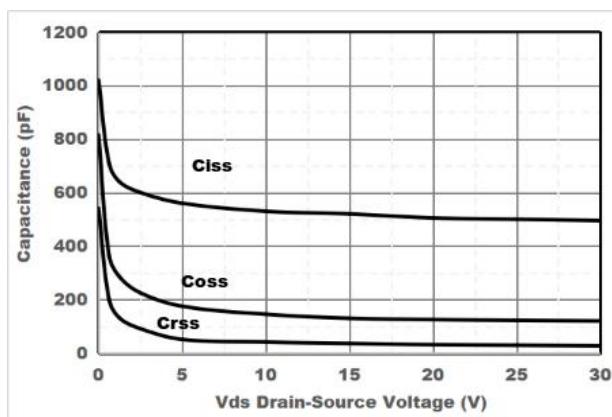


Figure3. Capacitance Characteristics

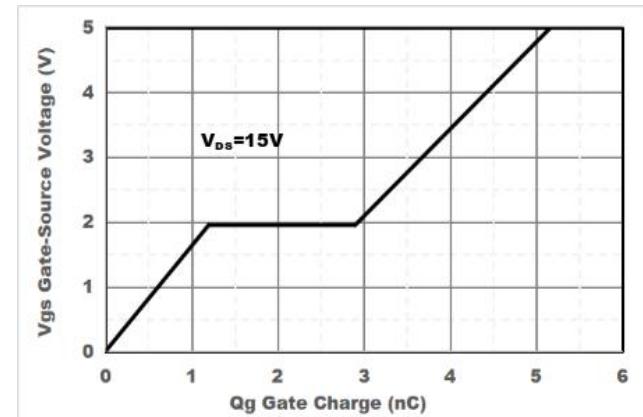


Figure4. Gate Charge

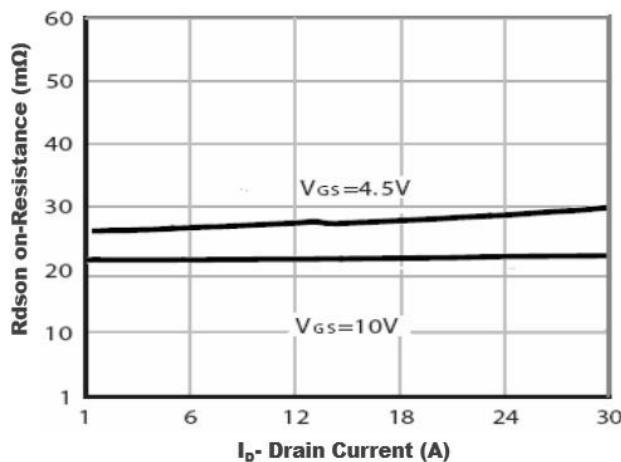


Figure5. Drain-Source on Resistance

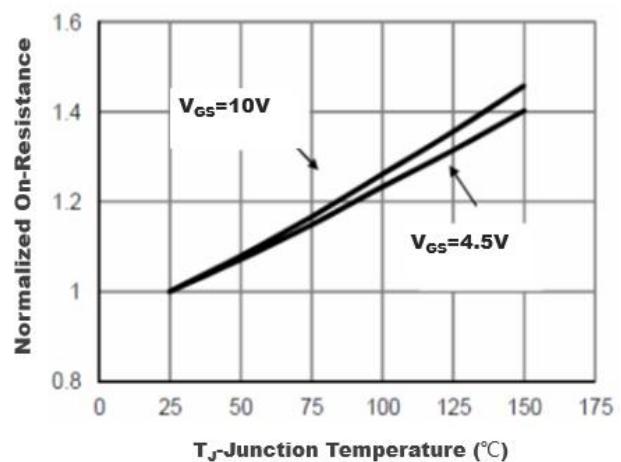
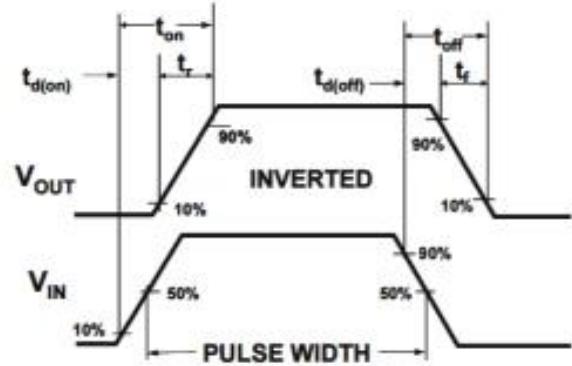
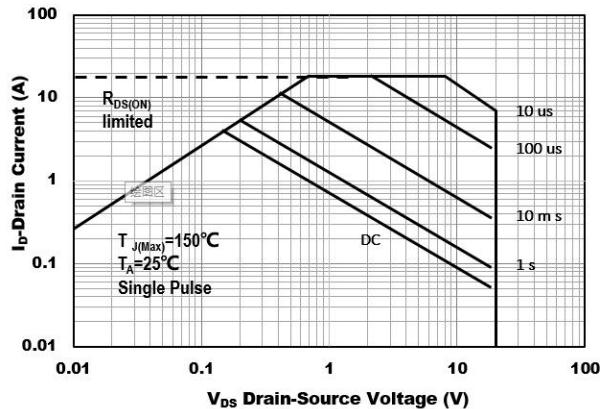
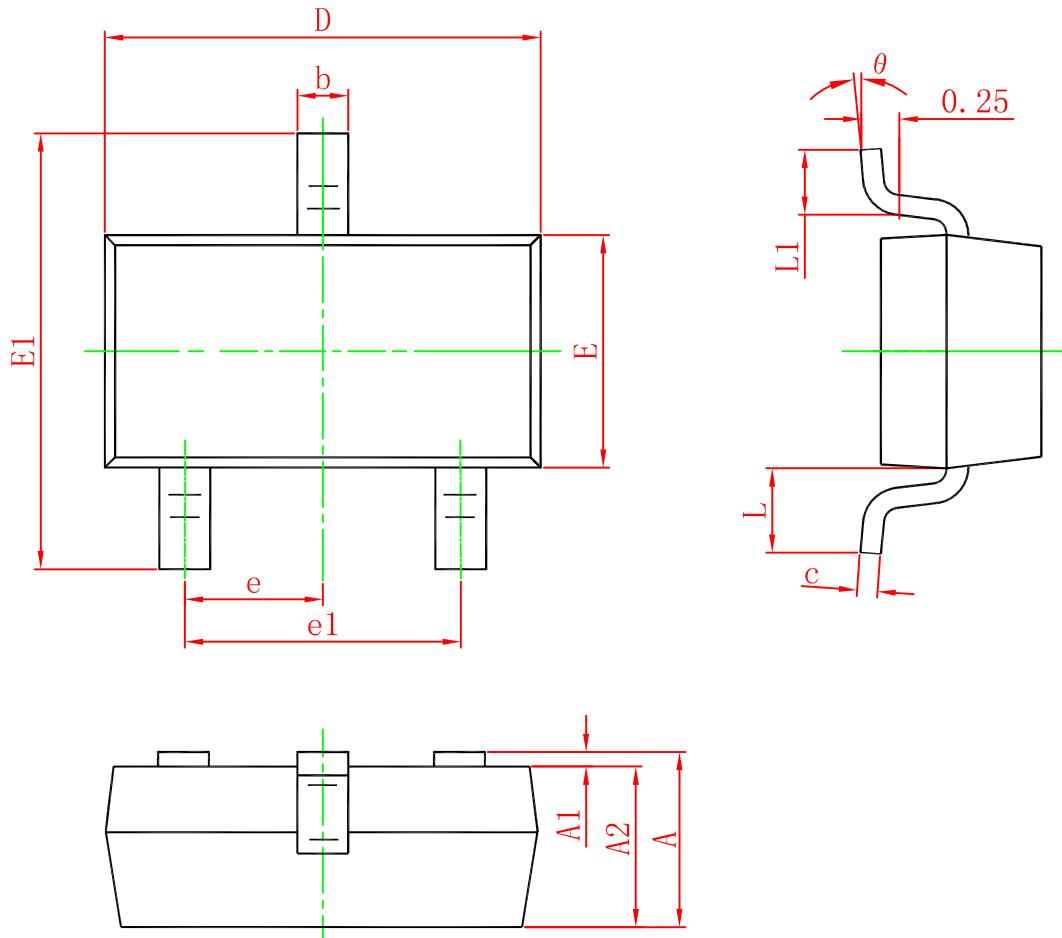


Figure6. Drain-Source on Resistance

Typical Characteristics



SOT-23 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°